

12-22-2004

PATENTS ONLY



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document or copy thereof.

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12-10-4

<p>1. Name of party or parties conveying an interest:</p> <p><b>Jae-Suk LEE</b></p>	<p>2. Name and address of party or parties receiving an interest:</p> <p>Name: Dongbu Electronics Co., Ltd. a Korean corporation 838, Yeoksam 1-dong, Kangnam-ku, Seoul 135-080, Korea</p>
<p>3. Description of the interest conveyed:</p> <p><input checked="" type="checkbox"/> Assignment <input type="checkbox"/> Merger <input type="checkbox"/> Change of Name <input type="checkbox"/> Security Agreement</p> <p>Execution Date: December 9, 2004</p>	<p>Other:</p>
<p>4. Application number(s) or patent number(s). Additional sheet attached? YES___ NO <u>X</u></p> <p>A. Patent Application no.(s): Not yet assigned filed December 10, 2004</p>	<p>If the document is being filed together with a new application, the execution date of the application is:</p> <p>B. Patent no.(s):</p>
<p>5. Name and address of party to whom correspondence concerning this cover sheet should be mailed:</p> <p>Name: James A. Flight Reg. No. 37,622 HANLEY, FLIGHT &amp; ZIMMERMAN, LLC Street Address: 20 North Wacker Drive Suite 4220 City: Chicago State: Illinois Zip: 60606</p>	<p>6. Number of applications and/or patents identified on this cover sheet: 1</p> <p>7. Amount of fee enclosed or authorized to be charged: \$40.00</p> <p>8. Any additional required fee may be charged, or any overpayment credited to our deposit account: 50-2455</p>

9. To the best of my knowledge and belief, the information contained on this cover sheet is true and correct and any copy submitted is a true copy of the original document.

Date: December 10, 2004

*James A. Flight*  
James A. Flight  
Registration No. 37,622

Total number of pages including cover sheet, attachments, and document: 3

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# ASSIGNMENT

Serial No:

Filed: December 10, 2004

Title: **METAL INTERCONNECTION LINES OF SEMICONDUCTOR DEVICES AND METHODS OF FORMING THE SAME**

For good and valuable consideration, the receipt and sufficiency whereof are hereby acknowledged, the undersigned hereby assigns to DONGBU ELECTRONICS CO., LTD. of 838, Yeoksam 1-dong, Kangnam-ku, Seoul, 135-080, Korea (hereinafter "Assignee"), its successors and assigns, the entire right, title and interest in the invention or improvements of the undersigned disclosed in an application for Letters Patent of the United States, and in said application and any and all other applications, which the undersigned may file, either solely or jointly with others, on said invention or improvements, and in any and all Letters Patent of the United States, which may be obtained on any of said applications, and in any reissue or extension thereof.

The undersigned hereby authorizes and requests the Commissioner of Patents and Trademarks to issue said Letters Patent to said assignee.

The undersigned hereby authorizes and requests the attorneys of record in said application to insert in this assignment the execution date and/or filing date and serial number of said application when officially known.

The undersigned warrants himself to be the owner of the interest herein assigned and to have the right to make this assignment and further warrants that there are no outstanding prior assignments, licenses, or other rights in the interest herein assigned.

For said consideration the undersigned hereby agrees, upon the request and at the expense of said assignee, its successors and assigns, to execute any and all divisional, continuation, continuation-in-part and substitute applications for said invention or improvements, and any necessary oath or affidavit relating thereto, and any application for the reissue or extension of any Letters Patent that may be granted upon said application, that said assignee, its successors or assigns, may deem necessary or expedient, and for said consideration the undersigned further agrees upon the request of said assignee, its successors or assigns, in the event of any application or Letters Patent assigned herein becoming involved in Interference, to cooperate to the best of the ability of the undersigned with said assignee, its successors or assigns, in the matters of preparing and executing the preliminary statement and giving and producing evidence in support thereof, the undersigned hereby agreeing to perform, upon request, any and all affirmative acts to obtain said Letters Patent, and vest all rights therein hereby conveyed in said assignee, its

successors and assigns, whereby said Letters Patent will be held and enjoyed by said assignee, its successors and assigns, to the full end of the term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by the undersigned if this assignment and sale had not been made.

Date: December 9, 2004

Signature

Lee Jae Suk

Name

LEE, Jae-Suk

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